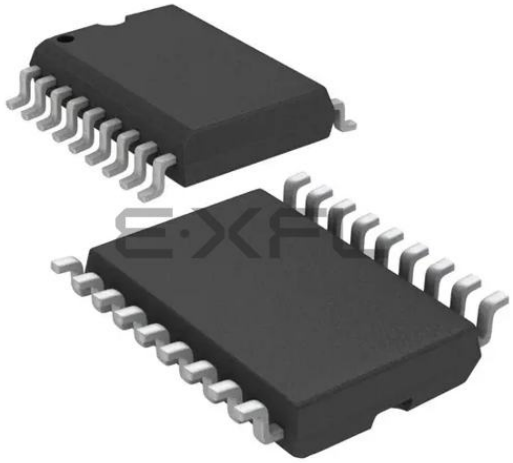

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	24KB (8K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f3012-20i-so

High-Performance, 16-bit Digital Signal Controllers

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "*dsPIC30F Family Reference Manual*" (DS70046). For more information on the device instruction set and programming, refer to the "*16-bit MCU and DSC Programmer's Reference Manual*" (DS70157).

High-Performance Modified RISC CPU:

- Modified Harvard architecture
- C compiler optimized instruction set architecture
- Flexible addressing modes
- 83 base instructions
- 24-bit wide instructions, 16-bit wide data path
- Up to 24 Kbytes on-chip Flash program space
- Up to 2 Kbytes of on-chip data RAM
- Up to 1 Kbytes of nonvolatile data EEPROM
- 16 x 16-bit working register array
- Up to 30 MIPS operation:
  - DC to 40 MHz external clock input
  - 4 MHz - 10 MHz oscillator input with PLL active (4x, 8x, 16x)
- Up to 21 interrupt sources:
  - 8 user-selectable priority levels
  - 3 external interrupt sources
  - 4 processor trap sources

DSP Features:

- Dual data fetch
- Modulo and Bit-Reversed modes
- Two 40-bit wide accumulators with optional saturation logic
- 17-bit x 17-bit single-cycle hardware fractional/ integer multiplier
- All DSP instructions are single cycle
  - Multiply-Accumulate (MAC) operation
- Single-cycle ±16 shift

Peripheral Features:

- High-current sink/source I/O pins: 25 mA/25 mA
- Three 16-bit timers/counters; optionally pair up 16-bit timers into 32-bit timer modules
- 16-bit Capture input functions
- 16-bit Compare/PWM output functions
- 3-wire SPI modules (supports four Frame modes)
- I^2C™ module supports Multi-Master/Slave mode and 7-bit/10-bit addressing
- Up to two addressable UART modules with FIFO buffers

Analog Features:

- 12-bit Analog-to-Digital Converter (ADC) with:
  - 200 ksps conversion rate
  - Up to 10 input channels
  - Conversion available during Sleep and Idle
- Programmable Low-Voltage Detection (PLVD)
- Programmable Brown-out Reset

Special Microcontroller Features:

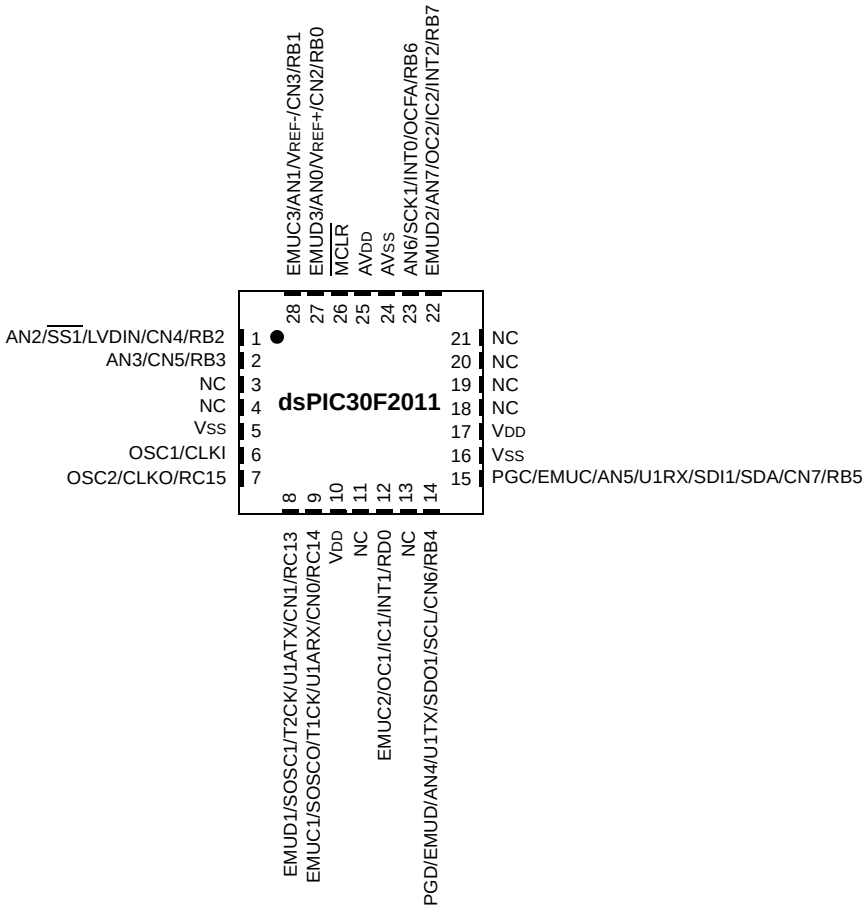
- Enhanced Flash program memory:
  - 10,000 erase/write cycle (min.) for industrial temperature range, 100K (typical)
- Data EEPROM memory:
  - 100,000 erase/write cycle (min.) for industrial temperature range, 1M (typical)
- Self-reprogrammable under software control
- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Flexible Watchdog Timer (WDT) with on-chip low-power RC oscillator for reliable operation
- Fail-Safe Clock Monitor operation:
  - Detects clock failure and switches to on-chip low-power RC oscillator
- Programmable code protection
- In-Circuit Serial Programming™ (ICSP™)
- Selectable Power Management modes:
  - Sleep, Idle and Alternate Clock modes

CMOS Technology:

- Low-power, high-speed Flash technology
- Wide operating voltage range (2.5V to 5.5V)
- Industrial and Extended temperature ranges
- Low-power consumption

Pin Diagrams

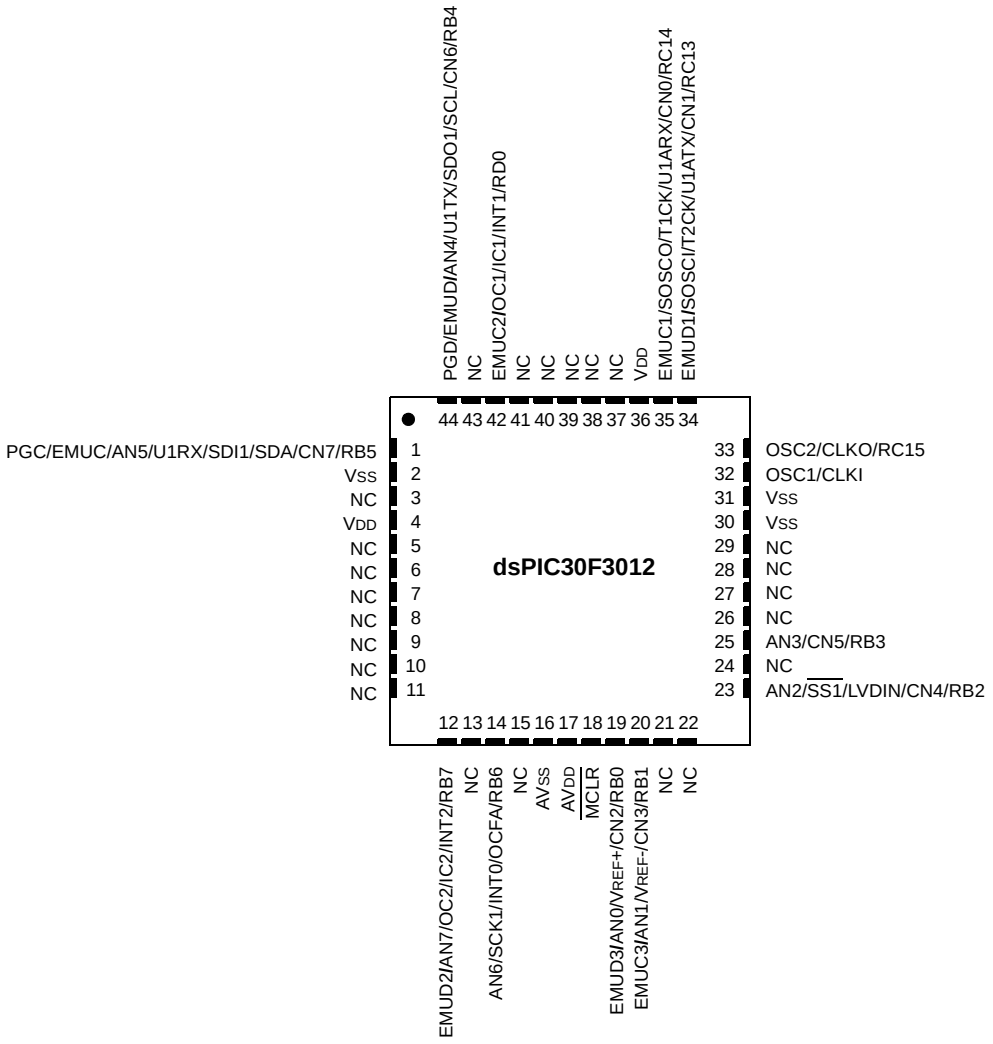
28-Pin QFN-S(1)



Note 1: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

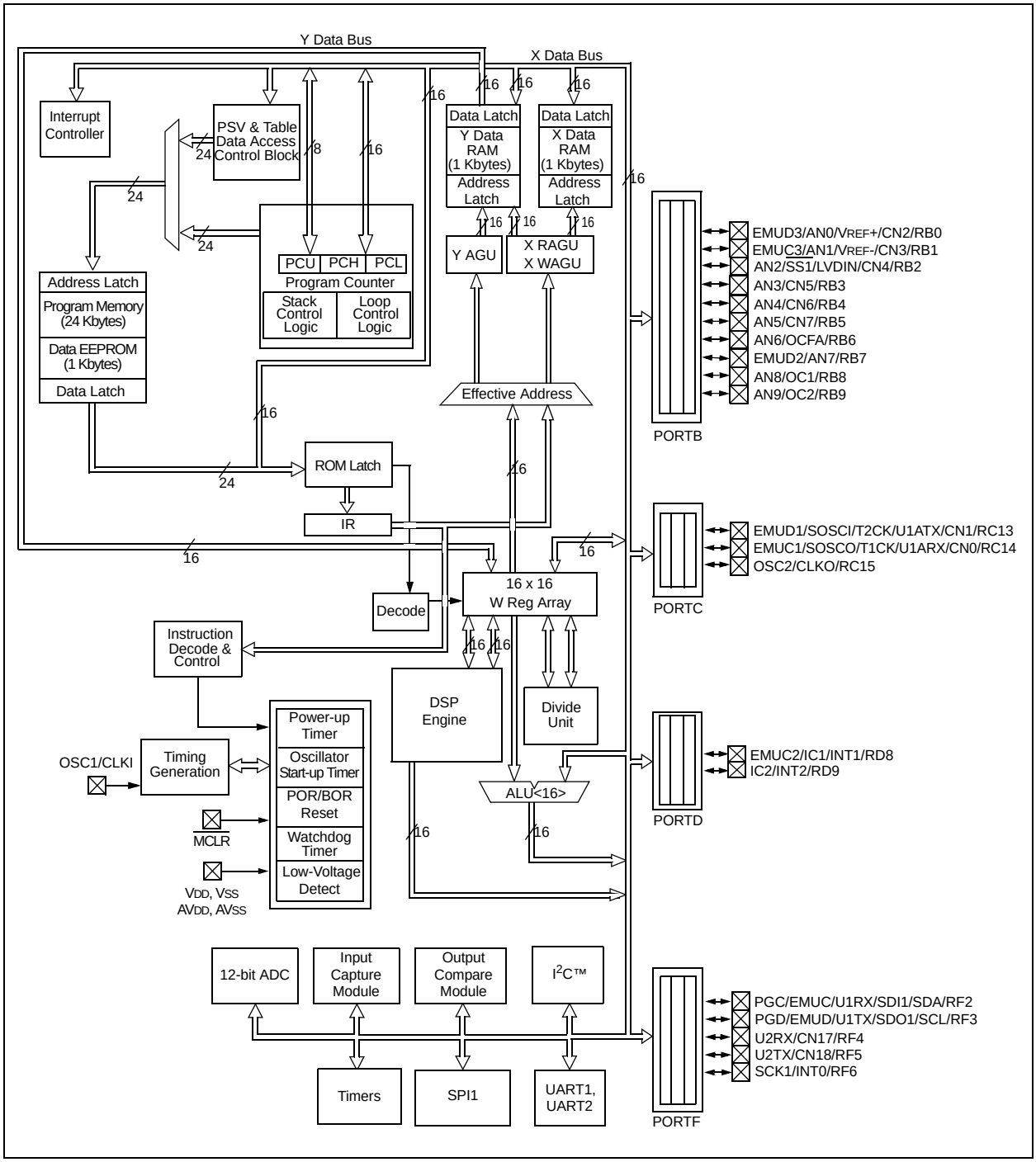
Pin Diagram

44-Pin QFN(1)



Note 1: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

FIGURE 1-4: dsPIC30F3013 BLOCK DIAGRAM



2.3 Divide Support

The dsPIC DSC devices feature a 16/16-bit signed fractional divide operation, as well as 32/16-bit and 16/16-bit signed and unsigned integer divide operations, in the form of single instruction iterative divides. The following instructions and data sizes are supported:

1. DIVF - 16/16 signed fractional divide
2. DIV.sd - 32/16 signed divide
3. DIV.ud - 32/16 unsigned divide
4. DIV.s - 16/16 signed divide
5. DIV.u - 16/16 unsigned divide

The 16/16 divides are similar to the 32/16 (same number of iterations), but the dividend is either zero-extended or sign-extended during the first iteration.

The divide instructions must be executed within a REPEAT loop. Any other form of execution (e.g., a series of discrete divide instructions) will not function correctly because the instruction flow depends on RCOUNT. The divide instruction does not automatically set up the RCOUNT value and it must, therefore, be explicitly and correctly specified in the REPEAT instruction, as shown in Table 2-1 (REPEAT executes the target instruction {operand value+1} times). The REPEAT loop count must be setup for 18 iterations of the DIV/DIVF instruction. Thus, a complete divide operation requires 19 cycles.

Note:	The divide flow is interruptible; however, the user needs to save the context as appropriate.

TABLE 2-1: DIVIDE INSTRUCTIONS

Instruction	Function
DIVF	Signed fractional divide: Wm/Wn →W0; Rem →W1
DIV.sd	Signed divide: (Wm+1:Wm)/Wn →W0; Rem →W1
DIV.s	Signed divide: Wm/Wn →W0; Rem →W1
DIV.ud	Unsigned divide: (Wm+1:Wm)/Wn →W0; Rem →W1
DIV.u	Unsigned divide: Wm/Wn →W0; Rem →W1

2.4.2.4 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space may also be saturated but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly. For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF. For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000. The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

2.4.3 BARREL SHIFTER

The barrel shifter is capable of performing up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either of the two DSP accumulators, or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of '0' does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between bit positions 16 to 31 for right shifts, and bit positions 0 to 16 for left shifts.

5.6 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. A programming operation is nominally 2 msec in duration and the processor stalls (waits) until the operation is finished. Setting the WR bit (NVMCON<15>) starts the operation and the WR bit is automatically cleared when the operation is finished.

5.6.1 PROGRAMMING ALGORITHM FOR PROGRAM FLASH

The user can erase or program one row of program Flash memory at a time. The general process is:

1. Read one row of program Flash (32 instruction words) and store into data RAM as a data “image”.
2. Update the data image with the desired new data.
3. Erase program Flash row.
   a) Set up NVMCON register for multi-word, program Flash, erase, and set WREN bit.
   b) Write address of row to be erased into NVMADRU/NVMDR.
   c) Write 0x55 to NVMKEY.
   d) Write 0xAA to NVMKEY.
   e) Set the WR bit. This begins erase cycle.
   f) CPU stalls for the duration of the erase cycle.
   g) The WR bit is cleared when erase cycle ends.
4. Write 32 instruction words of data from data RAM “image” into the program Flash write latches.
5. Program 32 instruction words into program Flash.
   a) Set up NVMCON register for multi-word, program Flash, program, and set WREN bit.
   b) Write 0x55 to NVMKEY.
   c) Write 0xAA to NVMKEY.
   d) Set the WR bit. This begins program cycle.
   e) CPU stalls for duration of the program cycle.
   f) The WR bit is cleared by the hardware when program cycle ends.
6. Repeat steps 1 through 5 as needed to program desired amount of program Flash memory.

5.6.2 ERASING A ROW OF PROGRAM MEMORY

Example 5-1 shows a code sequence that can be used to erase a row (32 instructions) of program memory.

EXAMPLE 5-1: ERASING A ROW OF PROGRAM MEMORY

```
; Setup NVMCON for erase operation, multi word write
; program memory selected, and writes enabled
       MOV     #0x4041,W0                  ;
       MOV     W0,NVMCON                   ; Init NVMCON SFR
; Init pointer to row to be ERASED
       MOV     #tblpage(PROG_ADDR),W0      ;
       MOV     W0,NVMADRU                  ; Initialize PM Page Boundary SFR
       MOV     #tbloffset(PROG_ADDR),W0    ; Intialize in-page EA[15:0] pointer
       MOV     W0, NVMADR                  ; Initialize NVMADR SFR
       DISI    #5                          ; Block all interrupts with priority <7 for
                                           ; next 5 instructions
       MOV     #0x55,W0
       MOV     W0,NVMKEY                   ; Write the 0x55 key
       MOV     #0xAA,W1                    ;
       MOV     W1,NVMKEY                   ; Write the 0xAA key
       BSET    NVMCON,#WR                  ; Start the erase sequence
       NOP                                 ; Insert two NOPs after the erase
       NOP                                 ; command is asserted
```

6.2 Erasing Data EEPROM

6.2.1 ERASING A BLOCK OF DATA EEPROM

In order to erase a block of data EEPROM, the NVMADRU and NVMADR registers must initially point to the block of memory to be erased. Configure NVMCON for erasing a block of data EEPROM and set the WR and WREN bits in the NVMCON register. Setting the WR bit initiates the erase, as shown in Example 6-2.

EXAMPLE 6-2: DATA EEPROM BLOCK ERASE

```
; Select data EEPROM block, WR, WREN bits
    MOV     #0x4045,W0
    MOV     W0,NVMCON                   ; Initialize NVMCON SFR

; Start erase cycle by setting WR after writing key sequence
    DISI    #5                          ; Block all interrupts with priority <7 for
                                        ; next 5 instructions
    MOV     #0x55,W0                    ;
    MOV     W0,NVMKEY                   ; Write the 0x55 key
    MOV     #0xAA,W1                    ;
    MOV     W1,NVMKEY                   ; Write the 0xAA key
    BSET    NVMCON,#WR                  ; Initiate erase sequence
    NOP
    NOP
; Erase cycle will complete in 2mS. CPU is not stalled for the Data Erase Cycle
; User can poll WR bit, use NVMIF or Timer IRQ to determine erasure complete
```

6.2.2 ERASING A WORD OF DATA EEPROM

The NVMADRU and NVMADR registers must point to the block. Select WR a block of data Flash and set the WR and WREN bits in the NVMCON register. Setting the WR bit initiates the erase, as shown in Example 6-3.

EXAMPLE 6-3: DATA EEPROM WORD ERASE

```
; Select data EEPROM word, WR, WREN bits
    MOV     #0x4044,W0
    MOV     W0,NVMCON

; Start erase cycle by setting WR after writing key sequence
    DISI    #5                          ; Block all interrupts with priority <7 for
                                        ; next 5 instructions
    MOV     #0x55,W0                    ;
    MOV     W0,NVMKEY                   ; Write the 0x55 key
    MOV     #0xAA,W1                    ;
    MOV     W1,NVMKEY                   ; Write the 0xAA key
    BSET    NVMCON,#WR                  ; Initiate erase sequence
    NOP
    NOP
; Erase cycle will complete in 2mS. CPU is not stalled for the Data Erase Cycle
; User can poll WR bit, use NVMIF or Timer IRQ to determine erasure complete
```

Enabling an interrupt is accomplished via the respective timer interrupt enable bit, T1IE. The timer interrupt enable bit is located in the IEC0 Control register in the interrupt controller.

10.0 TIMER2/3 MODULE

Note:	This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "*dsPIC30F Family Reference Manual* "(DS70046).

This section describes the 32-bit general purpose Timer module (Timer2/3) and associated Operational modes. Figure 10-1 depicts the simplified block diagram of the 32-bit Timer2/3 module. Figure 10-2 and Figure 10-3 show Timer2/3 configured as two independent 16-bit timers, Timer2 and Timer3, respectively.

The Timer2/3 module is a 32-bit timer (which can be configured as two 16-bit timers) with selectable operating modes. These timers are utilized by other peripheral modules, such as:

- Input Capture
- Output Compare/Simple PWM

The following sections provide a detailed description, including setup and Control registers, along with associated block diagrams for the operational modes of the timers.

The 32-bit timer has the following modes:

- Two independent 16-bit timers (Timer2 and Timer3) with all 16-bit operating modes (except Asynchronous Counter mode)
- Single 32-bit timer operation
- Single 32-bit synchronous counter

Further, the following operational characteristics are supported:

- ADC event trigger
- Timer gate operation
- Selectable prescaler settings
- Timer operation during Idle and Sleep modes
- Interrupt on a 32-bit period register match

These operating modes are determined by setting the appropriate bit(s) in the 16-bit T2CON and T3CON SFRs.

For 32-bit timer/counter operation, Timer2 is the ls word and Timer3 is the ms word of the 32-bit timer.

Note:	For 32-bit timer operation, T3CON control bits are ignored. Only T2CON control bits are used for setup and control. Timer2 clock and gate inputs are utilized for the 32-bit timer module, but an interrupt is generated with the Timer3 interrupt flag (T3IF) and the interrupt is enabled with the Timer3 interrupt enable bit (T3IE).

16-bit Timer Mode: In the 16-bit mode, Timer2 and Timer3 can be configured as two independent 16-bit timers. Each timer can be set up in either 16-bit Timer mode or 16-bit Synchronous Counter mode. See **Section 9.0 "Timer1 Module"** for details on these two operating modes.

The only functional difference between Timer2 and Timer3 is that Timer2 provides synchronization of the clock prescaler output. This is useful for high frequency external clock inputs.

32-bit Timer Mode: In the 32-bit Timer mode, the timer increments on every instruction cycle, up to a match value preloaded into the combined 32-bit Period register PR3/PR2, then resets to '0' and continues to count.

For synchronous 32-bit reads of the Timer2/Timer3 pair, reading the ls word (TMR2 register) causes the ms word to be read and latched into a 16-bit holding register, termed TMR3HLD.

For synchronous 32-bit writes, the holding register (TMR3HLD) must first be written to. When followed by a write to the TMR2 register, the contents of TMR3HLD is transferred and latched into the MSB of the 32-bit timer (TMR3).

32-bit Synchronous Counter Mode: In the 32-bit Synchronous Counter mode, the timer increments on the rising edge of the applied external clock signal which is synchronized with the internal phase clocks. The timer counts up to a match value preloaded in the combined 32-bit period register, PR3/PR2, then resets to '0' and continues.

When the timer is configured for the Synchronous Counter mode of operation and the CPU goes into the Idle mode, the timer stops incrementing unless the TSIDL bit (T2CON<13>) = 0. If TSIDL = 1, the timer module logic resumes the incrementing sequence upon termination of the CPU Idle mode.

TABLE 10-1: TIMER2/3 REGISTER MAP

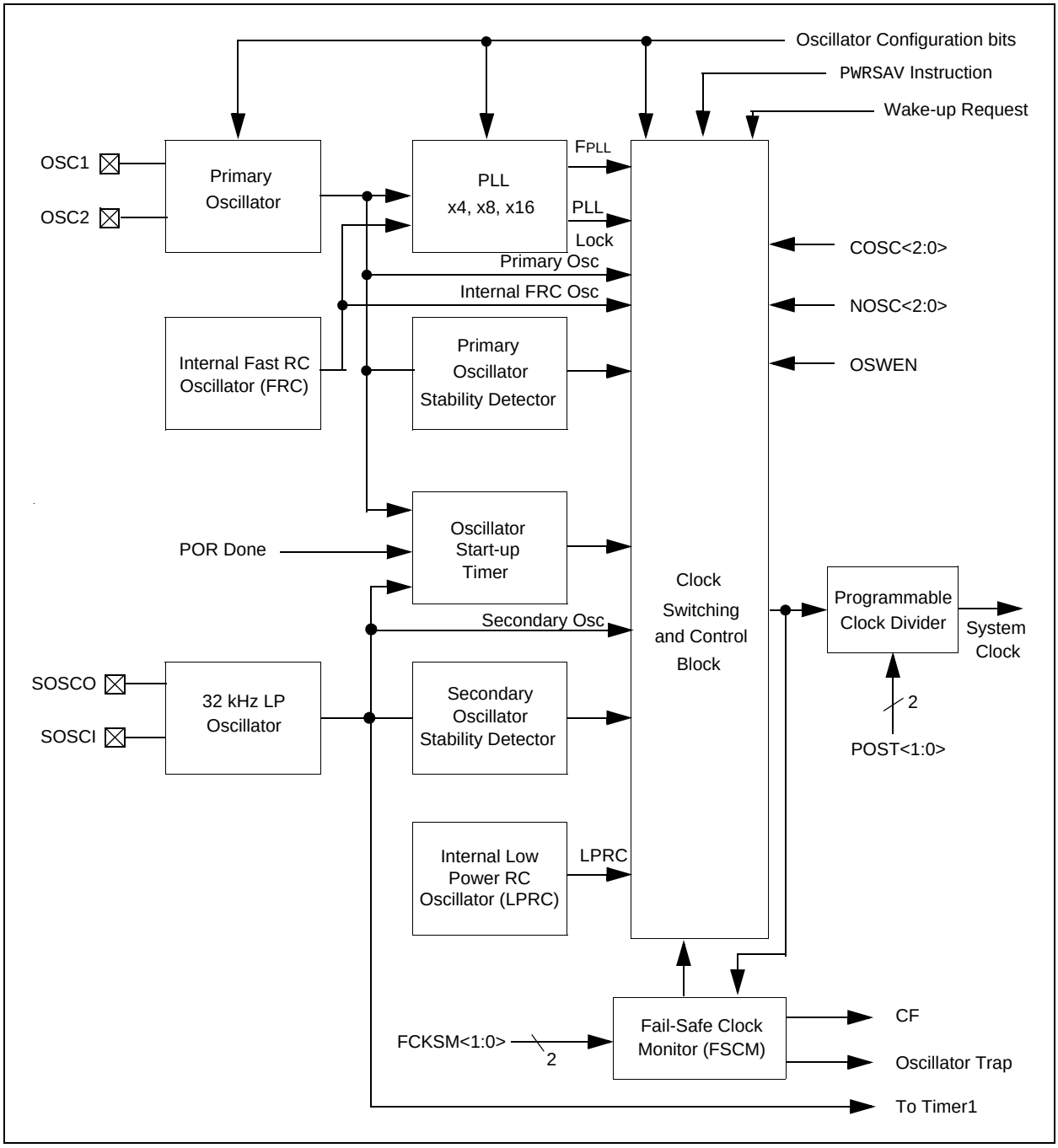
SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
TMR2	0106	Timer2 Register																uuuu uuuu uuuu uuuu
TMR3HLD	0108	Timer3 Holding Register (for 32-bit timer operations only)																uuuu uuuu uuuu uuuu
TMR3	010A	Timer3 Register																uuuu uuuu uuuu uuuu
PR2	010C	Period Register 2																1111 1111 1111 1111
PR3	010E	Period Register 3																1111 1111 1111 1111
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000 0000 0000 0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note: Refer to the "*dsPIC30F Family Reference Manual*" (DS70046) for descriptions of register bit fields.

NOTES:

FIGURE 17-1: OSCILLATOR SYSTEM BLOCK DIAGRAM



17.2 Oscillator Configurations

17.2.1 INITIAL CLOCK SOURCE SELECTION

While coming out of Power-on Reset or Brown-out Reset, the device selects its clock source based on:

a) FOS<2:0> Configuration bits that select one of four oscillator groups,

b) and FPR<4:0> Configuration bits that select one of 15 oscillator choices within the primary group.

The selection is as shown in Table 17-2.

17.2.2 OSCILLATOR START-UP TIMER (OST)

In order to ensure that a crystal oscillator (or ceramic resonator) has started and stabilized, an Oscillator Start-up Timer is included. It is a simple 10-bit counter that counts 1024 TOSC cycles before releasing the oscillator clock to the rest of the system. The time-out period is designated as TOST.

The TOST time is involved every time the oscillator has to restart (i.e., on POR, BOR and wake-up from Sleep). The Oscillator Start-up Timer is applied to the LP oscillator, XT, XTL and HS modes (upon wake-up from Sleep, POR and BOR) for the primary oscillator.

TABLE 17-2: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	FOS<2:0>			FPR<4:0>					OSC2 Function
ECIO w/PLL 4x	PLL	1	1	1	0	1	1	0	1	I/O
ECIO w/PLL 8x	PLL	1	1	1	0	1	1	1	0	I/O
ECIO w/PLL 16x	PLL	1	1	1	0	1	1	1	1	I/O
FRC w/PLL 4X	PLL	1	1	1	0	0	0	0	1	I/O
FRC w/PLL 8x	PLL	1	1	1	0	1	0	1	0	I/O
FRC w/PLL 16x	PLL	1	1	1	0	0	0	1	1	I/O
XT w/PLL 4x	PLL	1	1	1	0	0	1	0	1	OSC2
XT w/PLL 8x	PLL	1	1	1	0	0	1	1	0	OSC2
XT w/PLL 16x	PLL	1	1	1	0	0	1	1	1	OSC2
HS2 w/PLL 4x	PLL	1	1	1	1	0	0	0	1	OSC2
HS2 w/PLL 8x	PLL	1	1	1	1	0	0	1	0	OSC2
HS2 w/ PLL 16x	PLL	1	1	1	1	0	0	1	1	OSC2
HS3 w/PLL 4x	PLL	1	1	1	1	0	1	0	1	OSC2
HS3 w/PLL 8x	PLL	1	1	1	1	0	1	1	0	OSC2
HS3 w/PLL 16x	PLL	1	1	1	1	0	1	1	1	OSC2
ECIO	External	0	1	1	0	1	1	0	0	I/O
XT	External	0	1	1	0	0	1	0	0	OSC2
HS	External	0	1	1	0	0	0	1	0	OSC2
EC	External	0	1	1	0	1	0	1	1	CLKO
ERC	External	0	1	1	0	1	0	0	1	CLKO
ERCIO	External	0	1	1	0	1	0	0	0	I/O
XTL	External	0	1	1	0	0	0	0	0	OSC2
LP	Secondary	0	0	0	X	X	X	X	X	**(Note 1, 2)**
FRC	Internal FRC	0	0	1	X	X	X	X	X	**(Note 1, 2)**
LPRC	Internal LPRC	0	1	0	X	X	X	X	X	**(Note 1, 2)**

Note 1: The OSC2 pin is either usable as a general purpose I/O pin or is completely unusable, depending on the Primary Oscillator mode selection (FPR<4:0>).

2: OSC1 pin cannot be used as an I/O pin even if the secondary oscillator or an internal clock source is selected at all times.

FIGURE 17-3: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

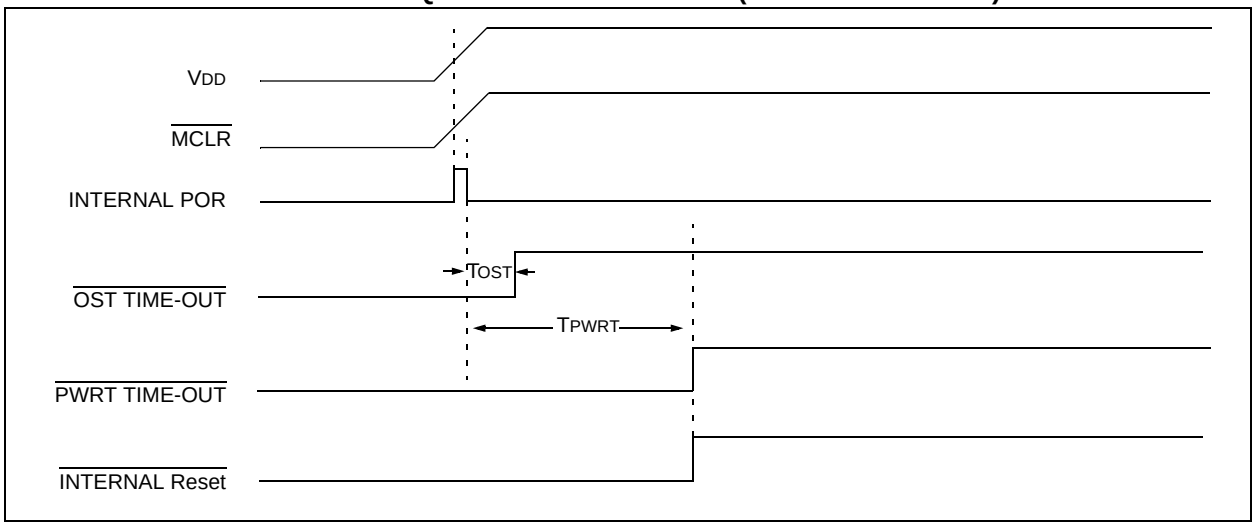


FIGURE 17-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

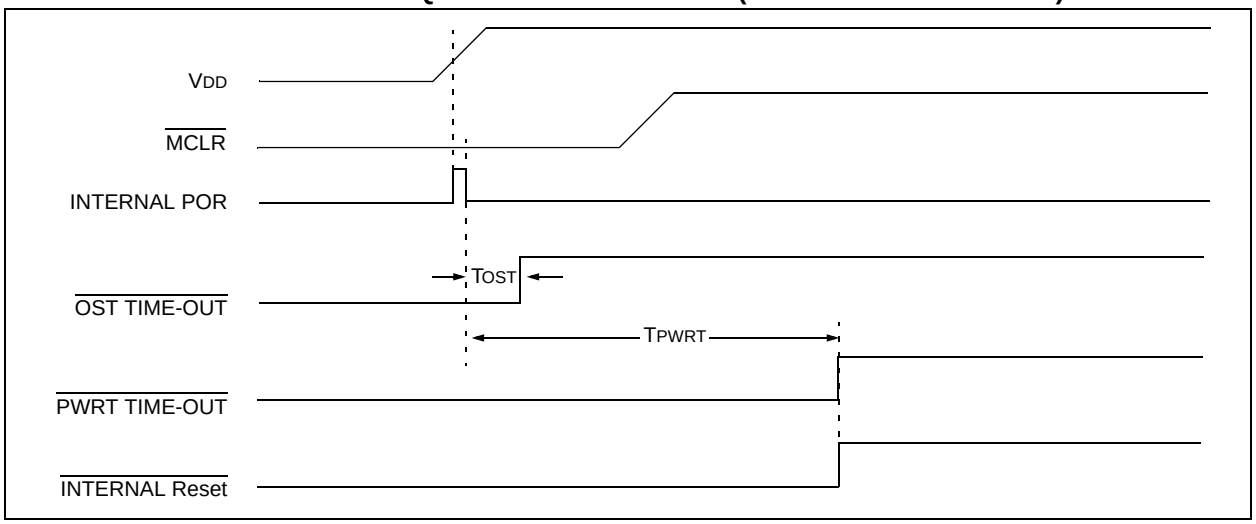
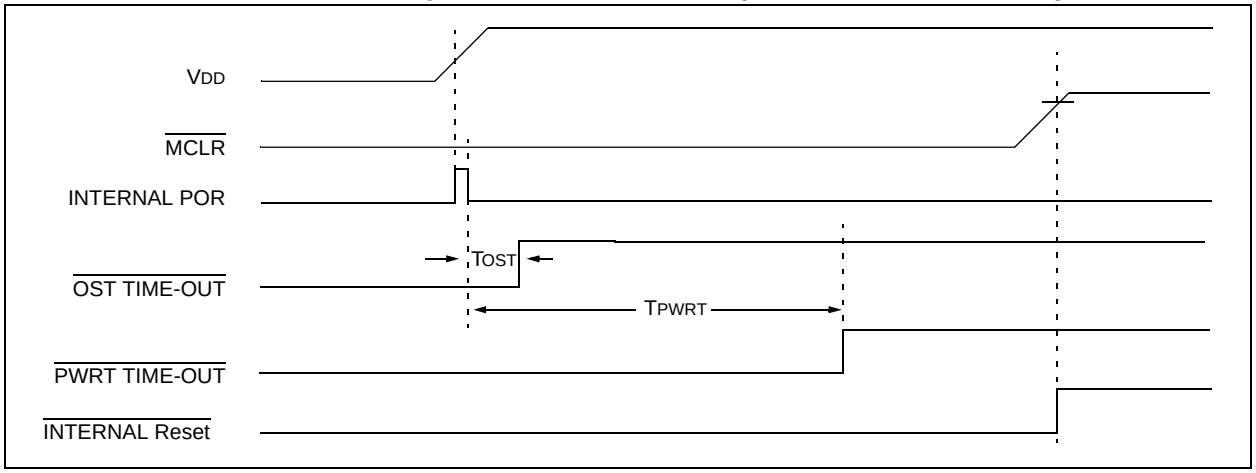


FIGURE 17-5: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2



All instructions are a single word, except for certain double-word instructions, which were made double-word instructions so that all the required information is available in these 48 bits. In the second word, the 8 MSbs are '0's. If this second word is executed as an instruction (by itself), it will execute as a NOP.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles with the additional instruction cycle(s) executed as a NOP. Notable exceptions are the BRA (unconditional/computed branch), indirect CALL/GOTO, all table reads and writes, and RETURN/RETFIE instructions, which are single-word instructions but take two or three cycles. Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles. The double-word instructions execute in two instruction cycles.

Note: For more details on the instruction set, refer to the *"MCU and DSC Programmer's Reference Manual"* (DS70157).

TABLE 18-1: SYMBOLS USED IN OPCODE DESCRIPTIONS

Field	Description
#text	Means literal defined by "text"
(text)	Means "content of text"
[text]	Means "the location addressed by text"
{ }	Optional field or operation
<n:m>	Register bit field
.b	Byte mode selection
.d	Double-Word mode selection
.S	Shadow register select
.w	Word mode selection (default)
Acc	One of two accumulators {A, B}
AWB	Accumulator write-back destination address register ∈ {W13, [W13]+=2}
bit4	4-bit bit selection field (used in word addressed instructions) ∈ {0...15}
C, DC, N, OV, Z	MCU Status bits: Carry, Digit Carry, Negative, Overflow, Sticky Zero
Expr	Absolute address, label or expression (resolved by the linker)
f	File register address ∈ {0x0000...0x1FFF}
lit1	1-bit unsigned literal ∈ {0,1}
lit4	4-bit unsigned literal ∈ {0...15}
lit5	5-bit unsigned literal ∈ {0...31}
lit8	8-bit unsigned literal ∈ {0...255}
lit10	10-bit unsigned literal ∈ {0...255} for Byte mode, {0:1023} for Word mode
lit14	14-bit unsigned literal ∈ {0...16384}
lit16	16-bit unsigned literal ∈ {0...65535}
lit23	23-bit unsigned literal ∈ {0...8388608}; LSB must be 0
None	Field does not require an entry, may be blank
OA, OB, SA, SB	DSP Status bits: ACCA Overflow, ACCB Overflow, ACCA Saturate, ACCB Saturate
PC	Program Counter
Slit10	10-bit signed literal ∈ {-512...511}
Slit16	16-bit signed literal ∈ {-32768...32767}
Slit6	6-bit signed literal ∈ {-16...16}

TABLE 18-2: INSTRUCTION SET OVERVIEW

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles	Status Flags Affected
1	ADD	ADD	Acc	Add Accumulators	1	1	OA,OB,SA,SB
		ADD	f	f = f + WREG	1	1	C,DC,N,OV,Z
		ADD	f,WREG	WREG = f + WREG	1	1	C,DC,N,OV,Z
		ADD	#lit10,Wn	Wd = lit10 + Wd	1	1	C,DC,N,OV,Z
		ADD	Wb,Ws,Wd	Wd = Wb + Ws	1	1	C,DC,N,OV,Z
		ADD	Wb,#lit5,Wd	Wd = Wb + lit5	1	1	C,DC,N,OV,Z
		ADD	Wso,#Slit4,Acc	16-bit Signed Add to Accumulator	1	1	OA,OB,SA,SB
2	ADDC	ADDC	f	f = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	f,WREG	WREG = f + WREG + (C)	1	1	C,DC,N,OV,Z
		ADDC	#lit10,Wn	Wd = lit10 + Wd + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,Ws,Wd	Wd = Wb + Ws + (C)	1	1	C,DC,N,OV,Z
		ADDC	Wb,#lit5,Wd	Wd = Wb + lit5 + (C)	1	1	C,DC,N,OV,Z
3	AND	AND	f	f = f .AND. WREG	1	1	N,Z
		AND	f,WREG	WREG = f .AND. WREG	1	1	N,Z
		AND	#lit10,Wn	Wd = lit10 .AND. Wd	1	1	N,Z
		AND	Wb,Ws,Wd	Wd = Wb .AND. Ws	1	1	N,Z
		AND	Wb,#lit5,Wd	Wd = Wb .AND. lit5	1	1	N,Z
4	ASR	ASR	f	f = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	f,WREG	WREG = Arithmetic Right Shift f	1	1	C,N,OV,Z
		ASR	Ws,Wd	Wd = Arithmetic Right Shift Ws	1	1	C,N,OV,Z
		ASR	Wb,Wns,Wnd	Wnd = Arithmetic Right Shift Wb by Wns	1	1	N,Z
		ASR	Wb,#lit5,Wnd	Wnd = Arithmetic Right Shift Wb by lit5	1	1	N,Z
5	BCLR	BCLR	f,#bit4	Bit Clear f	1	1	None
		BCLR	Ws,#bit4	Bit Clear Ws	1	1	None
6	BRA	BRA	C,Expr	Branch if Carry	1	1 (2)	None
		BRA	GE,Expr	Branch if greater than or equal	1	1 (2)	None
		BRA	GEU,Expr	Branch if unsigned greater than or equal	1	1 (2)	None
		BRA	GT,Expr	Branch if greater than	1	1 (2)	None
		BRA	GTU,Expr	Branch if unsigned greater than	1	1 (2)	None
		BRA	LE,Expr	Branch if less than or equal	1	1 (2)	None
		BRA	LEU,Expr	Branch if unsigned less than or equal	1	1 (2)	None
		BRA	LT,Expr	Branch if less than	1	1 (2)	None
		BRA	LTU,Expr	Branch if unsigned less than	1	1 (2)	None
		BRA	N,Expr	Branch if Negative	1	1 (2)	None
		BRA	NC,Expr	Branch if Not Carry	1	1 (2)	None
		BRA	NN,Expr	Branch if Not Negative	1	1 (2)	None
		BRA	NOV,Expr	Branch if Not Overflow	1	1 (2)	None
		BRA	NZ,Expr	Branch if Not Zero	1	1 (2)	None
		BRA	OA,Expr	Branch if Accumulator A overflow	1	1 (2)	None
		BRA	OB,Expr	Branch if Accumulator B overflow	1	1 (2)	None
		BRA	OV,Expr	Branch if Overflow	1	1 (2)	None
		BRA	SA,Expr	Branch if Accumulator A saturated	1	1 (2)	None
		BRA	SB,Expr	Branch if Accumulator B saturated	1	1 (2)	None
		BRA	Expr	Branch Unconditionally	1	2	None
		BRA	Z,Expr	Branch if Zero	1	1 (2)	None
		BRA	Wn	Computed Branch	1	2	None
7	BSET	BSET	f,#bit4	Bit Set f	1	1	None
		BSET	Ws,#bit4	Bit Set Ws	1	1	None
8	BSW	BSW.C	Ws,Wb	Write C bit to Ws<Wb>	1	1	None
		BSW.Z	Ws,Wb	Write Z bit to Ws<Wb>	1	1	None

TABLE 20-17: INTERNAL CLOCK TIMING EXAMPLES

Clock Oscillator Mode	FOSC (MHz)(1)	TCY (μsec)(2)	MIPS(3) w/o PLL	MIPS(3) w PLL x4	MIPS(3) w PLL x8	MIPS(3) w PLL x16
EC	0.200	20.0	0.05	—	—	—
	4	1.0	1.0	4.0	8.0	16.0
	10	0.4	2.5	10.0	20.0	—
	25	0.16	6.25	—	—	—
XT	4	1.0	1.0	4.0	8.0	16.0
	10	0.4	2.5	10.0	20.0	—

Note 1: Assumption: Oscillator Postscaler is divide by 1.

2: Instruction Execution Cycle Time: TCY = 1/MIPS.

3: Instruction Execution Frequency: MIPS = (FOSC * PLLx)/4 [since there are 4 Q clocks per instruction cycle].

TABLE 20-18: AC CHARACTERISTICS: INTERNAL FRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ FRC Freq. = 7.37 MHz(1)						
OS63	FRC	—	—	±2.00	%	-40°C ≤TA ≤+85°C	VDD = 3.0-5.5V
		—	—	±5.00	%	-40°C ≤TA ≤+125°C	VDD = 3.0-5.5V

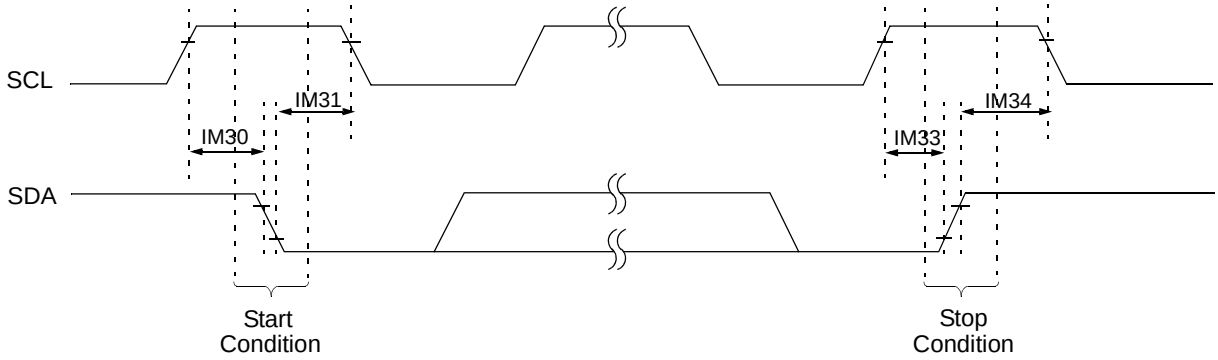
Note 1: Frequency calibrated at 7.372 MHz ±2%, 25°C and 5V. TUN bits (OSCCON<3:0>) can be used to compensate for temperature drift.

TABLE 20-19: AC CHARACTERISTICS: INTERNAL LPRC ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	LPRC @ Freq. = 512 kHz(1)					
OS65A		-50	—	+50	%	VDD = 5.0V, ±10%
OS65B		-60	—	+60	%	VDD = 3.3V, ±10%
OS65C		-70	—	+70	%	VDD = 2.5V

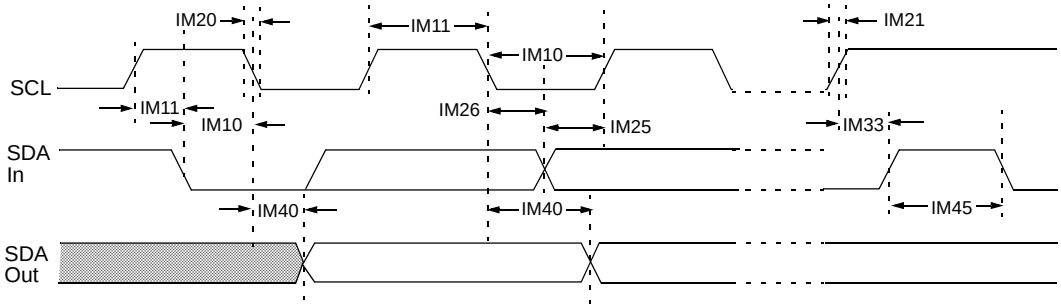
Note 1: Change of LPRC frequency as VDD changes.

FIGURE 20-16: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 20-3 for load conditions.

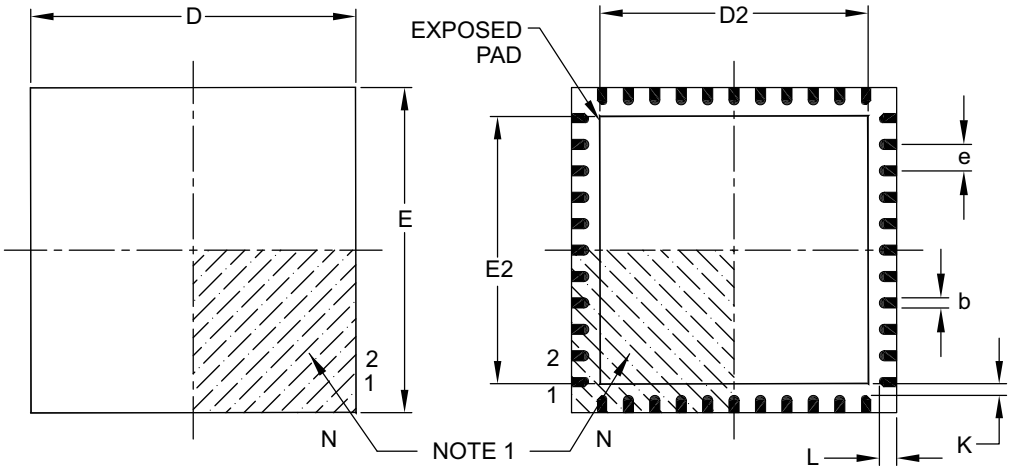
FIGURE 20-17: I²C™ BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



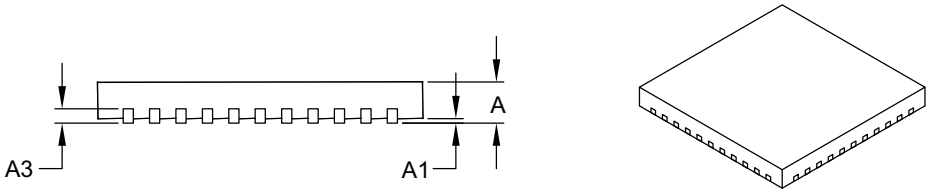
Note: Refer to Figure 20-3 for load conditions.

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW **BOTTOM VIEW**



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B